



LGA

LAND GRID ARRAY

SPECIFICATION FORM

NAME _____

TITLE _____

COMPANY _____

PHONE _____

EMAIL _____

FAX _____

1. Quantity Required _____

8. Solder Mask Opening _____

2. Body Size _____ x _____ mm

9. Substrate Thickness

1.5mm (Standard)

3. Number I/O Pads _____

0.8mm

other _____

4. Pitch 1.27mm 1.0mm 0.8mm 0.5mm

10. Application

5. Pad Material

Insertion into Socket

Sn63/Pb37 (Standard)

Ball Attach by Customer

Sn100 Tin

Solder to mother board

Au (gold)

Cu100 with OSP

11. Circuit

6. Pad Diameter

Daisy Chain

Standard

All Pads Shorted

other _____ mm

All Pads Isolated

Any Available

7. Solder Mask

None Taiyo PSR4000 AUS5

12. Substrate Material

FR4

Polyimide

Part Number Configuration

LGA

625

T

1.27

- DC61

G

8

Substrate

I/O

Packaging

Pitch

Circuit

Pad Material

Substrate

Plastic

T = Trays

mm

DC = Daisy Chain Pads

BUS = All Pads Shorted

ISO = All Pads Isolated

Blank = Standard Sn63/Pb37

T = Sn100 Tin

G = Au Gold

C = Cu100

Blank = 1.5mm thick (Standard)

8 = 0.8mm thick

**I
N
F
O**

LGA - Land Grid Arrays for socket insertion, Ball Attach and soldering to mother board.

Available in a variety of configurations and pad heights. Contact TopLine for details.